

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A method of manufacturing a mini-card with a semiconductor memory device comprising the steps of:

providing an array of substrates including a plurality of individual substrates ~~connected together~~ separated from each other, and being interconnected only by one or more segments;

mounting a semiconductor memory device on each of the individual substrates;

covering the individual substrates with respective cases; and

dividing, after the step of covering is completed, the substrate array to provide encased individual substrates each completing the mini-card having the semiconductor memory device embedded therein.

2. (Original) The method of manufacturing a mini-card with a semiconductor memory device according to claim 1, wherein, during the covering step, each substrate is sandwiched between top and bottom case segments.

3. (Original) The method of manufacturing a mini-card with a semiconductor memory device according to claim 1, wherein, during the covering step, each substrate is molded into case.

4. (Currently Amended) A mini-card with a semiconductor memory device characterized in that the mini-card is manufactured by a method comprising the steps of:

providing an array of substrates including a plurality of individual substrates ~~connected together~~ separated from each other, and being interconnected only by one or more segments;

mounting a semiconductor memory device on each of the individual substrates;

covering the individual substrates with respective cases; and

dividing, after the step of covering is completed, the substrate array to provide encased individual substrates each completing the mini-card having the semiconductor memory device embedded therein.

5. (Cancelled)